

# **Dual Diode Modules**

Replaces December 1998 version, DS5104-2.0

DS5104-3.0 January 2000

## **FEATURES**

- Dual Device Module
- Electrically Isolated Package
- Pressure Contact Construction
- International Standard Footprint
- Alumina (non-toxic) Isolation Medium

### **APPLICATIONS**

- Rectifier Bridges
- DC Power Bridges
- Plating Rectifiers
- Traction Systems

#### **VOLTAGE RATINGS**

Type Number	Repetitive Peak Voltages V <sub>RRM</sub>	Conditions
MP03/260-16	1600	
MP03/260-14	1400	$T_{vj} = 150^{\circ}C$ $I_{RM} = 30\text{mA}$
MP03/260-12	1200	
MP03/260-10	1000	$V_{RSM} = V_{RRM} + 100V$

Lower voltage grades available. For full description of part numbers see "Ordering instructions" on page 3.

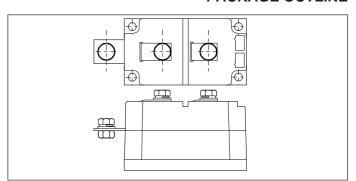
#### **KEY PARAMETERS**

$V_{RRM}$	1600V
I <sub>FSM</sub>	8100A
	267A
I <sub>F(AV)</sub> (per arm) V <sub>icel</sub>	2500V

### **CIRCUIT OPTIONS**

Code	Circuit		
НВ			
G			
GN			

#### **PACKAGE OUTLINE**



Module outline type code: MP03. See Package Details for further information.

# **CURRENT RATINGS - PER ARM**

Symbol	Parameter	Conditions		Max.	Units
	Mean forward current	Halfwave, resistive load	T <sub>case</sub> = 75°C	267	А
			T <sub>case</sub> = 85°C	240	А
F(AV)			T <sub>heatsink</sub> = 75°C	235	А
			T <sub>heatsink</sub> = 85°C	211	А
I <sub>F(RMS)</sub>	RMS value	T <sub>case</sub> = 75°C		420	А

# **SURGE RATINGS - PER ARM**

Symbol	Parameter	Conditions		Max.	Units
	Surge (non-repetitive) forward current	10ms half sine; T <sub>j</sub> = 150°C	V <sub>R</sub> = 0	8100	А
FSM			V <sub>R</sub> = 50% V <sub>RRM</sub>	6500	А
_	I <sup>2</sup> t for fusing	10ms half sine; T <sub>j</sub> = 150°C	V <sub>R</sub> = 0	328000	A <sup>2</sup> s
l <sup>2</sup> t			V <sub>R</sub> = 50% V <sub>RRM</sub>	211000	A <sup>2</sup> s

# **THERMAL & MECHANICAL RATINGS**

Symbol	Parameter	Conditions	Max.	Units
		dc	0.21	°C/W
$R_{th(j-c)}$	Thermal resistance - junction to case per Diode	halfwave	0.22	°C/W
	het plode	3 phase	0.23	°C/W
R <sub>th(c-hs)</sub>	Thermal resistance - case to heatsink per Diode	Mounting torque = 5Nm with mounting compound	0.05	°C/W
T <sub>vj</sub>	Virtual junction temperature		150	°C
T <sub>sto</sub>	Storage temperature range		-40 to 150	°C
V <sub>isol</sub>	Isolation voltage	Commoned terminals to base plate AC RMS, 1min, 50Hz	2.5	kV

# **CHARACTERISTICS**

Symbol	Parameter	Conditions	Max.	Units
V <sub>FM</sub>	Forward voltage	At 600A, T <sub>case</sub> = 25°C	1.3	V
I <sub>RM</sub>	Peak reverse current	At $V_{RRM}$ , $T_j = 150^{\circ}C$	30	mA
V <sub>TO</sub>	Threshold voltage	At T <sub>vj</sub> = 150°C	0.84	V
r <sub>T</sub>	On-state slope resistance	At T <sub>vj</sub> = 150°C	0.667	mΩ

#### ORDERING INSTRUCTIONS

Part number is made up as follows:

MP03 HB 260 - 16

MP = Pressure contact module

03 = Outline type

HB = Circuit configuration code (see "circuit options" - front page)

260 = Nominal average current rating at  $T_{case} = 75^{\circ}C$ 

 $16 = V_{RRM}/100$ 

### Examples:

MP03 HB260-10 MP03 G260-14 MP023GN260-12

Note: Preferred type is HB configuration. G & GN types are available for specific applications, only when requested.

#### MOUNTING RECOMMENDATIONS

- Adequate heatsinking is required to maintain the base temperature at 75°C if full rated current is to be achieved. Power dissipation may be calculated by use of V<sub>TO</sub> and r<sub>T</sub> information in accordance with standard formulae. We can provide assistance with calculations or choice of heatsink if required.
- The heatsink surface must be smooth and flat; a surface finish of N6 (32μin) and a flatness within 0.05mm (0.002") are recommended.
- Immediately prior to mounting, the heatsink surface should be lightly scrubbed with fine emery, Scotch Brite or a mild chemical etchant and then cleaned with a solvent to remove oxide build up and foreign material. Care should be taken to ensure no foreign particles remain.

- An even coating of thermal compound (eg. Unial) should be applied to both the heatsink and module mounting surfaces. This should ideally be 0.05mm (0.002") per surface to ensure optimum thermal performance.
- After application of thermal compound, place the module squarely over the mounting holes, (or 'T' slots) in the heatsink. Using a torque wrench, slowly tighten the recommended fixing bolts at each end, rotating each in turn no more than 1/4 of a revolution at a time. Continue until the required torque of 5Nm (44lb.ins) is reached at both ends.
- It is not acceptable to fully tighten one fixing bolt before starting to tighten the others. Such action may DAMAGE the module.

# **CURVES**

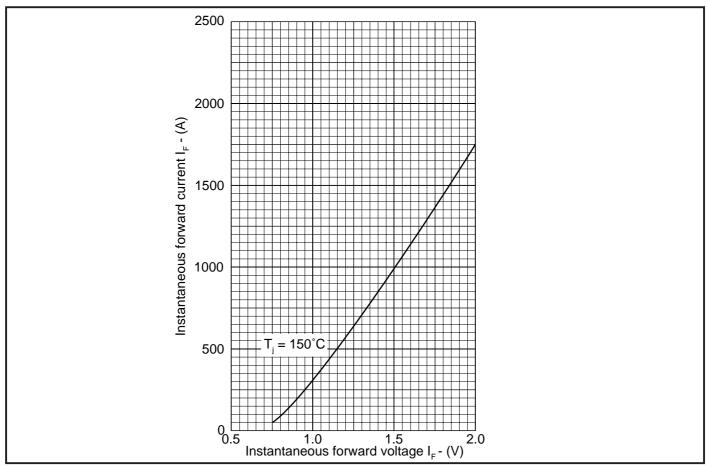


Fig. 1 Maximum (limit) forward characteristics (Per diode)

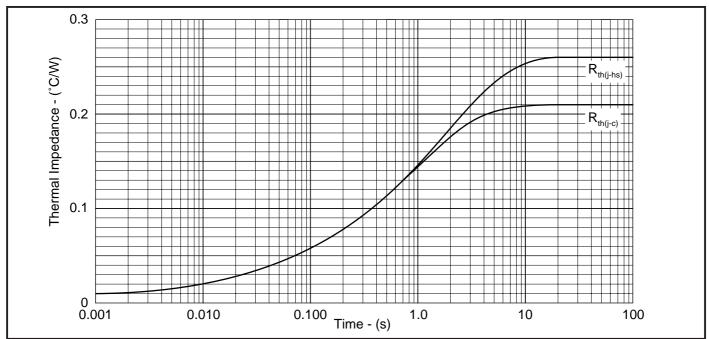


Fig. 2 Transient thermal impedance (DC) - (Per diode)

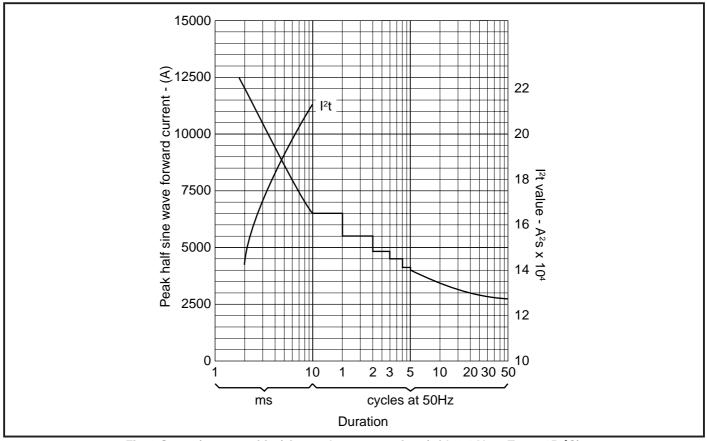


Fig. 3 Surge (non-repetitive) forward current vs time (with 0% V<sub>RRM</sub>, T<sub>case</sub> = 150°C)

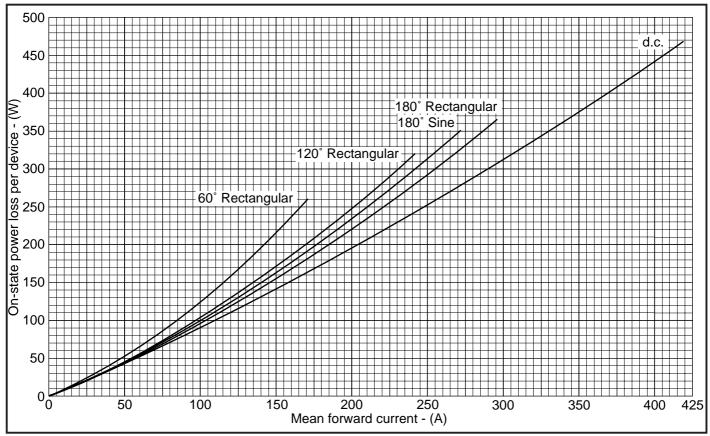


Fig. 4 On-state power loss per arm vs forward current at various conduction angles, 50/60Hz

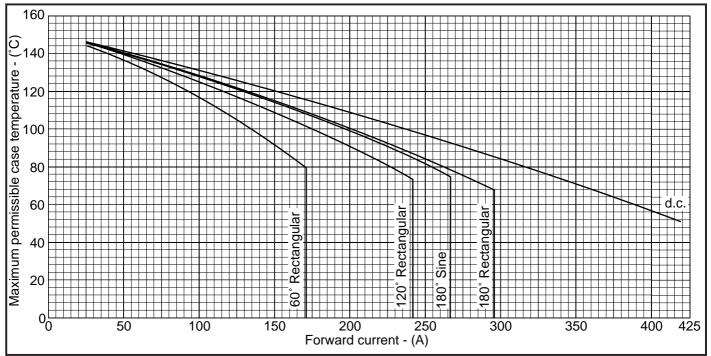


Fig. 5 Maximum permissible case temperature vs forward current per arm at various conduction angles, 50/60Hz

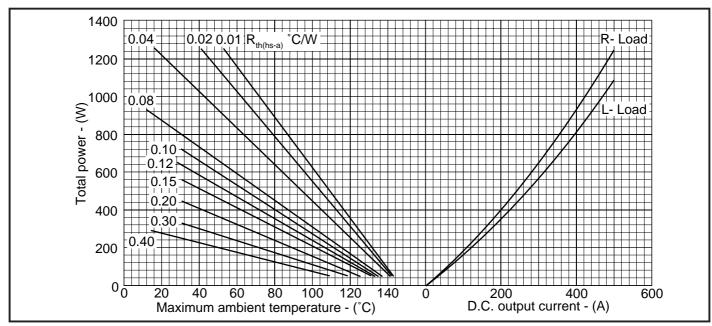


Fig. 6 50/60Hz single phase bridge dc output current vs power loss and maximum permissible ambient temperature for various values of heatsink thermal resistance.

(Note:  $R_{th(hs:a)}$  values given above are true heatsink thermal resistances to ambient and already account for  $R_{th(c:hs)}$  module contact thermal).

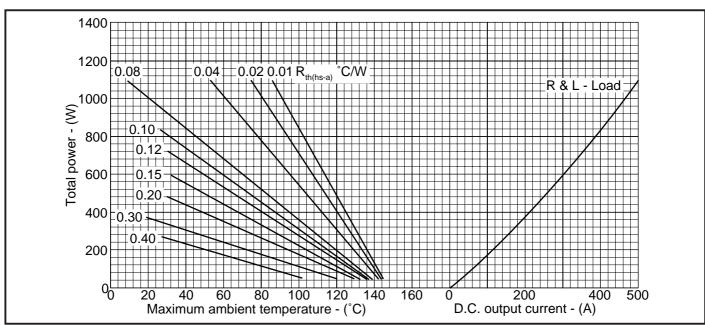
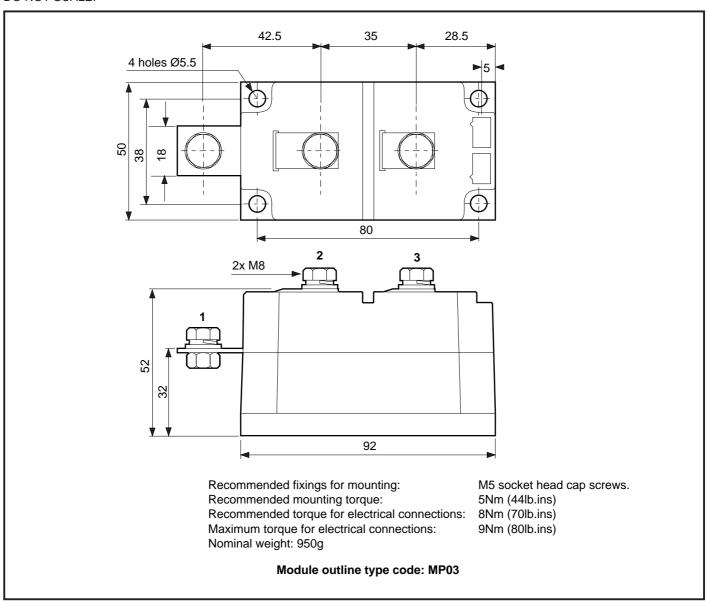


Fig. 7 50/60Hz 3- phase bridge dc output current vs power loss and maximum permissible ambient temperature for various values of heatsink thermal resistance.

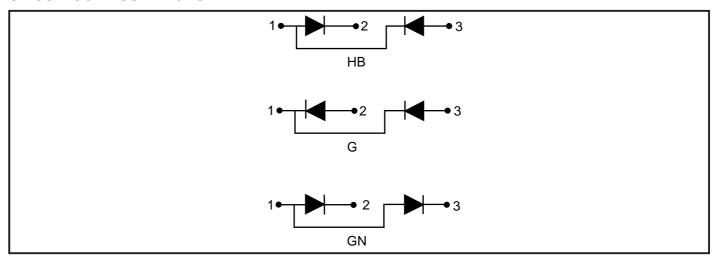
 $(\text{Note: R}_{\text{th(hs-a)}} \text{ values given above are true heatsink thermal resistances to ambient and already account for R}_{\text{th(c-hs)}} \text{ module contact thermal)}.$ 

# **PACKAGE DETAILS**

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



# **CIRCUIT CONFIGURATIONS**





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